

REMARKS/ARGUMENTS

Claims 20-31 are pending in the subject application. Claim 26 is currently amended. In particular, claim 26 is rewritten in independent form. Claims 20 and 26 are independent.

Claims 20-31 are presented to the Examiner for further prosecution on the merits.

A. Introduction

In the outstanding Office Action Made Final, the Examiner rejected claim 30 under 35 U.S.C. § 112, first paragraph; rejected claims 20-29 under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent No. 6,891,235 to Furukawa et al. (“the Furukawa et al. reference”) in view of U.S. Patent No. 6,316,297 to Matsuda (“the Matsuda reference”); and indicated that claim 31 recites allowable subject matter, but objected to claim 31 as being dependent upon a rejected base claim.

B. Asserted Rejection of Claim 30 Under 35 U.S.C. § 112, First Paragraph

In the outstanding Office action, the Examiner rejected claim 30 under 35 U.S.C. § 112, first paragraph, as failing to comply with the written description requirement. Applicants respectfully traverse this rejection for at least the reasons set forth below.

Claim 30 was added by the amendment filed September 28, 2005. In the September 28th amendment, applicants indicated that support for claim 30 could be found in, e.g., paragraph [0038] of the specification. That paragraph recites:

[0038] Thus, the lower insulating layer 170 covers an entire surface of the surface insulating layer 150 and also fills the undercut region of the gate pattern 140. In case the undercut region is narrow, the surface insulating layer 150 alone may fill the undercut region.

In the outstanding Office action, the Examiner asserted that the limitation “the surface insulating layer completely fills the undercut region,” which is recited in claim 30,

is not described in the specification. *See the Office action of December 8, 2005, at paragraph 2, page 2.* Applicants respectfully disagree.

In particular, applicants respectfully submit that the disclosure in paragraph [0038] that “the surface insulating layer 150 alone may fill the undercut region” clearly supports the recitation of “wherein the surface insulating layer completely fills the undercut region” in claim 30. Accordingly, applicants respectfully submit that the subject matter of claim 30 was clearly described in the specification at the time the application was filed. Therefore, applicants respectfully request that this rejection be reconsidered and withdrawn.

C. Asserted Obviousness Rejection of Claims 20-29

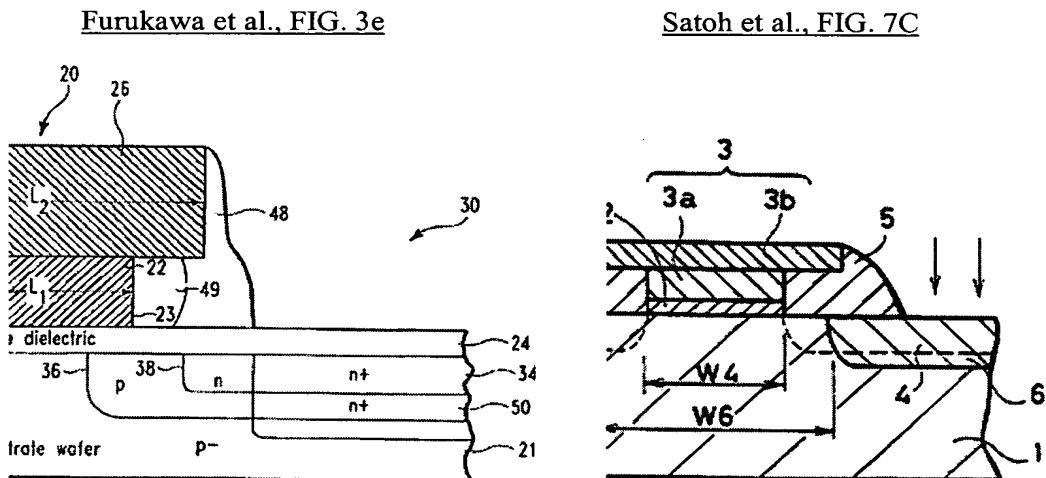
In the outstanding Office action, the Examiner rejected claims 20-29 under 35 U.S.C. § 103(a) as being unpatentable over the Furukawa et al. reference in view of the Matsuda reference. Applicants respectfully traverse this rejection for at least the reasons set forth below.

Claim 20 recites, in part:

an L-shaped lower spacer covering a top surface of the semiconductor substrate at both sides of the T-shaped gate electrode and covering sides of the wide portion of the T-shaped gate electrode, the L-shaped lower spacer having a first element disposed substantially perpendicular to the semiconductor substrate, and having a second element disposed substantially parallel to the semiconductor substrate, the second element extending from the first element laterally away from the T-shaped gate electrode;

In the outstanding Office action, the Examiner asserted that the Furukawa et al. reference discloses this aspect of claim 20, including, *inter alia*, an L-shaped lower spacer (indicating element 48 in FIG. 3e of the Furukawa et al. reference). *See the Office action of December 8, 2005, at paragraph 5, page 3.* Applicants respectfully disagree, and submit that element 48 is not L-shaped.

Moreover, applicants note that the Examiner has previously raised, and dropped, a substantially similar assertion regarding the previously-cited Satoh et al. reference, U.S. Patent No. 5,272,100. In particular, applicants note that the Examiner previously asserted that the Satoh et al. reference discloses, in FIG. 7C thereof, an L-shaped lower spacer (5). *See the Office action of June 29, 2005, at paragraph 5, page 4.* However, in response to applicants' September 28, 2005, amendment, which included, in particular, arguments and amendments to claim 20 regarding the L shape of the lower spacer, the Examiner dropped the assertions regarding the Satoh et al. reference. Pertinent parts of FIG. 3e of the Furukawa et al. reference and FIG. 7C of the Satoh et al. reference are reproduced below:



Applicants respectfully submit that the Furukawa et al. reference fails to disclose, or even suggest, an L-shaped lower spacer as recited in claim 20. Further, applicants respectfully submit that the Matsuda reference fails to provide this missing teaching. Therefore, applicants respectfully submit that claim 20 is allowable over the proposed combination of the Furukawa et al. and Matsuda references.

The remaining rejected claims, viz., claims 21-29, depend, either directly or indirectly, from claim 20, and are believed to be similarly allowable. Accordingly,

applicants respectfully request that this rejection be reconsidered and withdrawn, and a notice of allowance provided.

D. Amendment to Claim 26

By the instant amendment, claim 26 is rewritten in independent form. In particular, claim 26 has been rewritten to incorporate all the limitations of claim 20, from which it previously depended. Accordingly, claim 26 is believed to be allowable for at least the reasons set forth above regarding claim 20. Moreover, applicants respectfully submit that the outstanding rejection of claim 26 under 35 U.S.C. § 103(a) over the combination of the Furukawa et al. and Matsuda references is improper for at least the reasons set forth below.

Claim 26 differs from claim 20 by additionally reciting the following:

. . . further comprising a surface insulating layer intervened between the narrow portion of the gate electrode and the lower spacer.

In the outstanding Office action, the Examiner asserted that the Furukawa et al. reference discloses a surface insulating layer (48) intervened between the gate electrode (20) and the lower spacer (48). In particular, the Examiner asserted that:

as interpreting the claim in a broad scope, a surface insulating layer can also be the same as the lower spacer because the claims do not distinct the material of the lower spacer and the surface insulating layer. Therefore, the lower spacer and the surface insulating layer are considered as one layer.

See the Office action of December 8, 2005, at page 6.

In other words, the Examiner asserted that the surface insulating layer and the lower spacer are one and the same. Applicants respectfully submit that this construction of claim 26 is clearly improper.

In particular, applicants submit that the Examiner's construction of claim 26 effectively removes all meaning from the claim, and, by equating the surface insulating layer with the lower spacer, effectively makes claim 26 read thus: "further comprising

Element A intervened between Element B and Element A.” Thus, the Examiner’s construction of claim 26 effectively eliminates the recitation of the surface insulating layer, thereby gutting claim 26 of meaning. This is contrary to well-settled law. See, e.g., *Phillips v. AWH Corp.*, 415 F.3d 1301 (Fed. Cir. 2005) (en banc), which states that “the presence of a dependent claim that adds a particular limitation gives rise to a presumption that the limitation in question is not present in the independent claim,” citing *Liebel-Flarsheim Co. v. Medrad, Inc.*, 358 F.3d 898, 910 (Fed. Cir. 2004).

In view of the above, applicants respectfully submit that Examiner must give proper weight to the recitation of a surface insulating layer in claim 26. Applicants respectfully request that the rejection of claim 26 be reconsidered and withdrawn, and request that a notice of allowance be provided.

E. Allowable Subject Matter

Applicants appreciate the Examiner’s indication of allowable subject matter in claim 31. However, applicants respectfully submit that all of the pending claims are in condition for allowance, and respectfully request that a notice to that effect be provided.

F. Entry Requested

Applicants respectfully submit that the pending claims are in condition for allowance, and that the instant amendment to claim 26 merely presents this claim in different form. Accordingly, entry of the above amendment after final is respectfully requested.

G. Conclusion

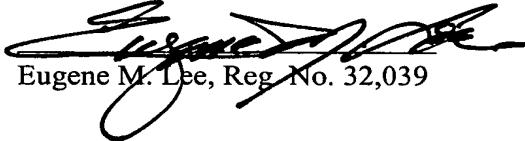
Since the cited prior art relied on to reject the claims of the subject application fails to anticipate or render obvious the present invention, applicants respectfully submit that claims 20-31 are in condition for allowance, and a notice to that effect is respectfully requested.

If the Examiner believes that additional discussions or information might advance the prosecution of the instant application, the Examiner is invited to contact the undersigned at the telephone number listed below to expedite resolution of any outstanding issues.

In view of the foregoing amendments and remarks, reconsideration of this application is earnestly solicited, and an early and favorable further action upon all the claims is hereby requested.

Respectfully submitted,
LEE & MORSE, P.C.

Date: February 1, 2006


Eugene M. Lee, Reg. No. 32,039

LEE & MORSE, P.C.
1101 WILSON BOULEVARD, SUITE 2000
ARLINGTON, VA 22209
703.525.0978 TEL
703.525.4265 FAX

PETITION and
DEPOSIT ACCOUNT CHARGE AUTHORIZATION

This document and any concurrently filed papers are believed to be timely. Should any extension of the term be required, applicant hereby petitions the Director for such extension and requests that any applicable petition fee be charged to Deposit Account No. 50-1645.

If fee payment is enclosed, this amount is believed to be correct. However, the Director is hereby authorized to charge any deficiency or credit any overpayment to Deposit Account No. 50-1645.

Any additional fee(s) necessary to effect the proper and timely filing of the accompanying-papers may also be charged to Deposit Account No. 50-1645.